



재료의 전기적 성질

emph4sis

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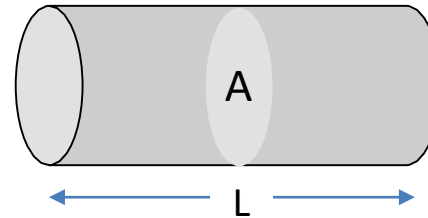
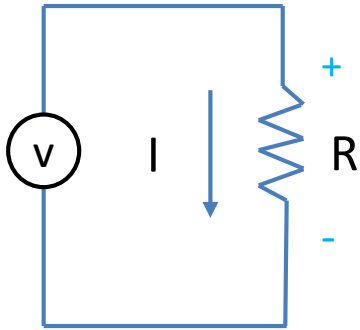
Gas Sensor Mechanism

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Ohm's law

Resistivity & Electrical Conductivity



$$R \propto \frac{L}{A}$$

$$\text{Voltage [V]} = \text{Current [A]} \times \text{Resistance [\Omega]}$$

The equation is presented with colored boxes: a blue box for 'V', a red box for 'I', and a green box for 'R'. The units are written below each term: 'Voltage[V]' in blue, 'Current [A]' in red, and 'Resistance [Ω]' in green.

Ohm's Law

Resistivity & Electrical Conductivity

- Resistivity

$$R = \rho \frac{L}{A} \quad \text{단위 : } [\Omega \cdot m]$$

- Electrical Conductivity

$$\sigma = \frac{1}{\rho} \quad \text{단위 : } [\Omega \cdot m]^{-1}$$

$$\begin{array}{c} \text{Current density} \\ J [A/m^2] \end{array} \quad \frac{V}{L} = \frac{I}{A} \rho$$

$E [V/m]$
Electric field intensity

Resistivity $[\Omega \cdot m]$

$$J = \sigma E$$

Current density $\propto$ Electric field intensity

Conductivity σ

Conductors

Silver

6.8×10^7

Copper

6.0×10^7

Iron

1.0×10^7

Semiconductors

Silicon

4.0×10^{-4}

Germanium

2.0×10^0

GaAs

1.0×10^{-6}

Insulators

Soda-lime glass

1.0×10^{-10}

Concrete

1.0×10^{-9}

Aluminum oxide

1.0×10^{-13}

Polystyrene

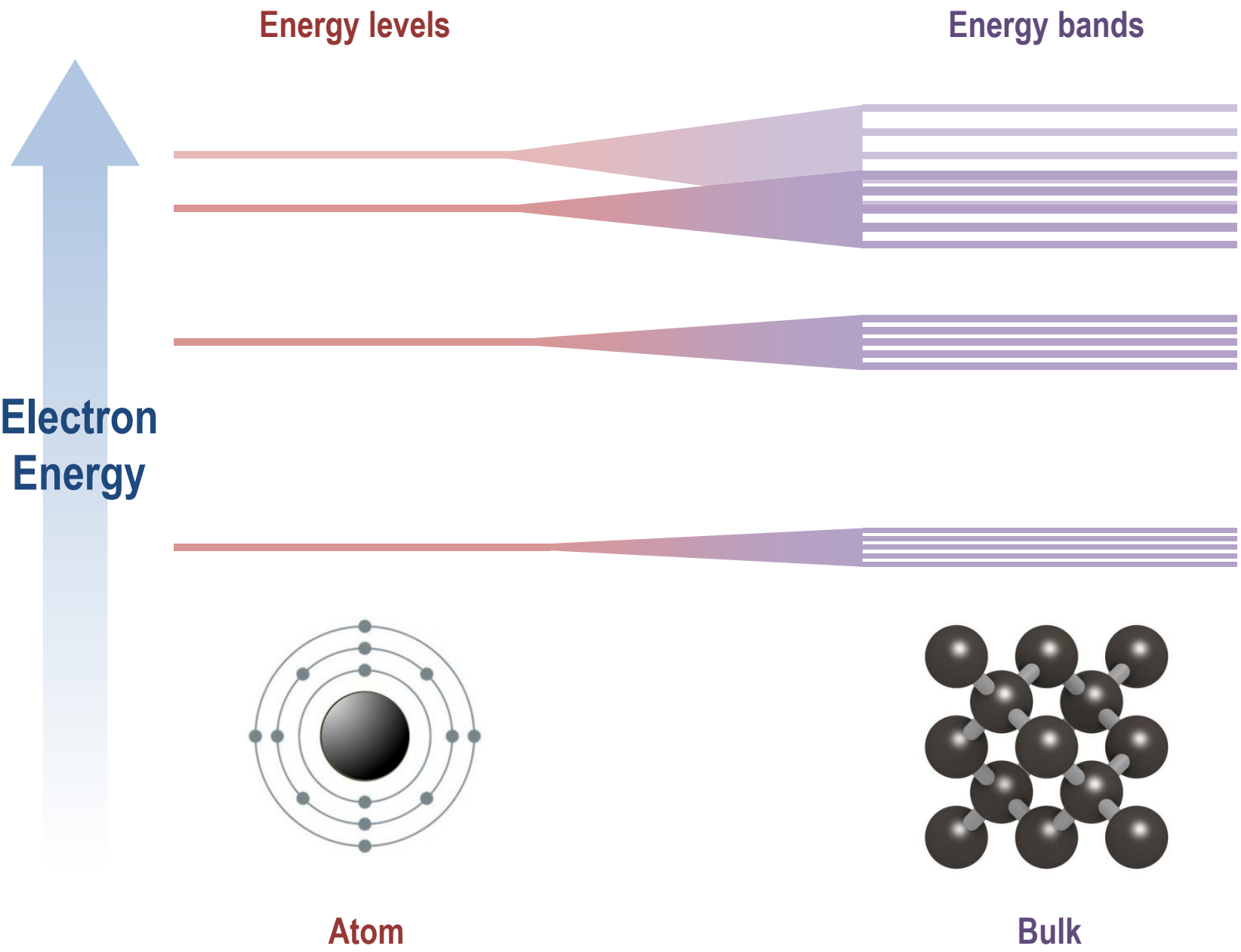
1.0×10^{-14}

Polyethylene

$10^{-15} \sim 10^{-17}$



Energy Band structure



Energy Band structure

- Conduction band**

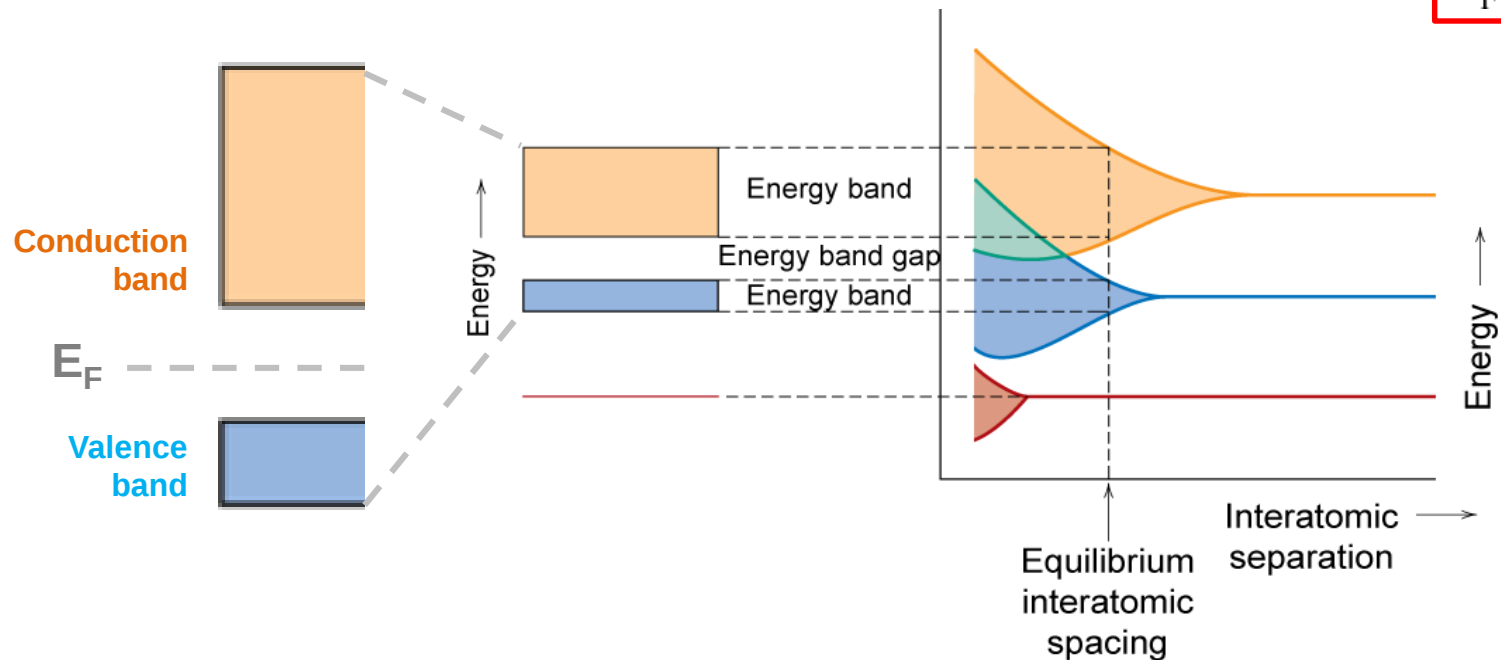
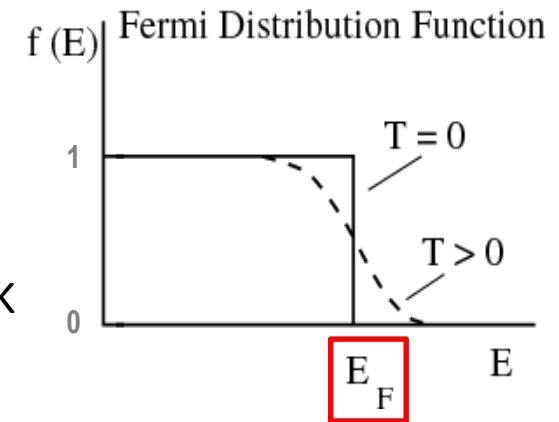
Electrons in valance band can jump up when excited

- Valence band**

The highest band where electrons occupy in ground state

- Fermi Energy (E_f)**

The highest energy level that an electron can occupy at 0K

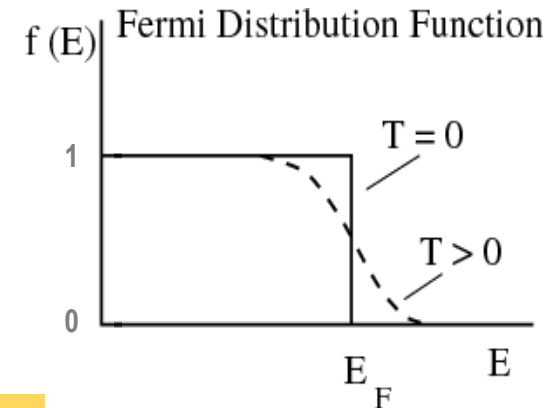
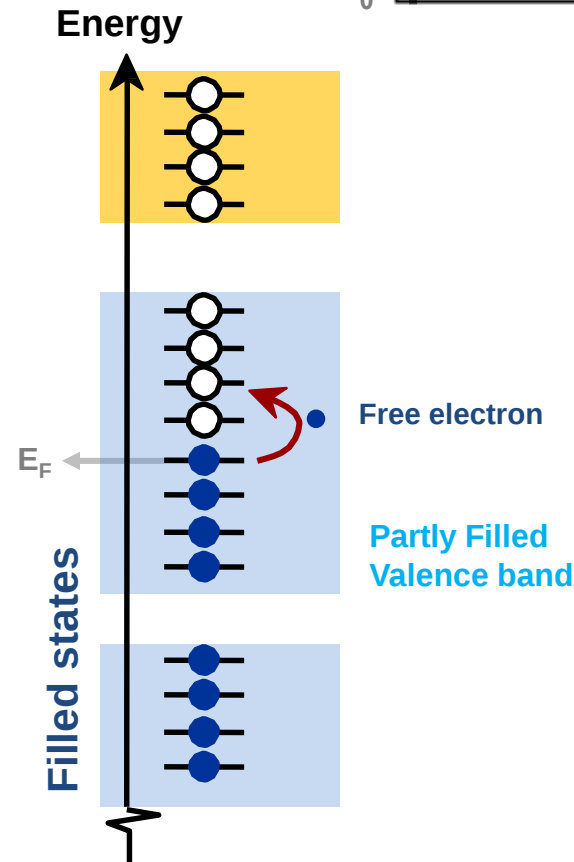
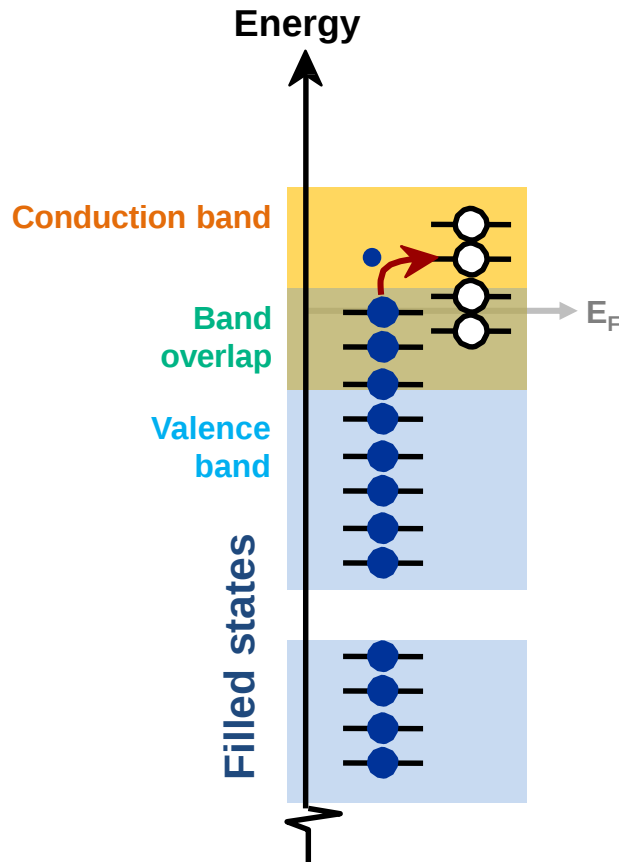


Energy Band structure

- **Conductors**

Already have free electrons over 0K

High conductivity

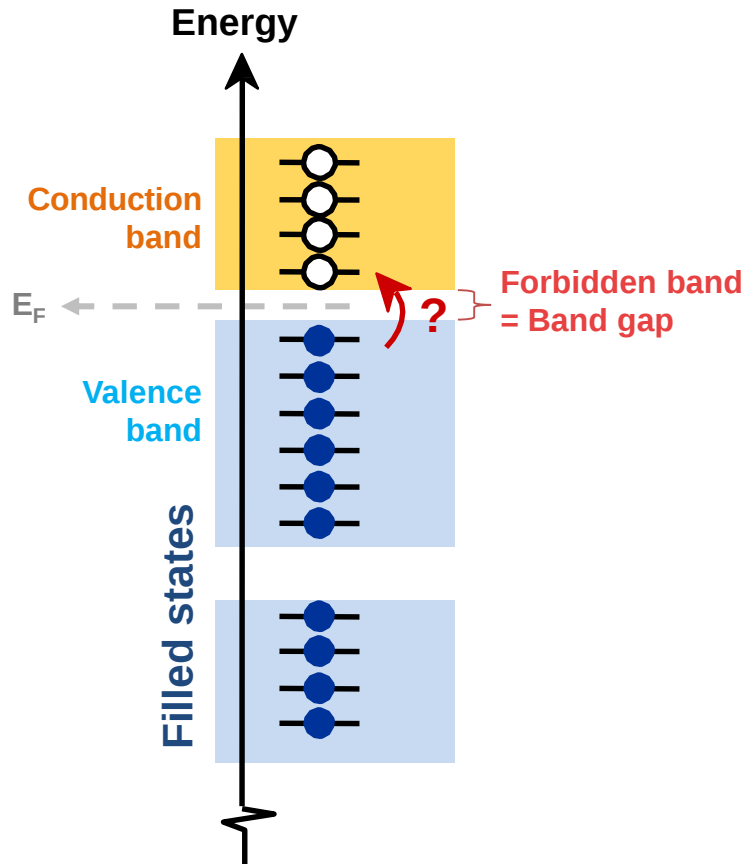


Energy Band structure

- **Semiconductors**

Small band gap (< 2 eV)

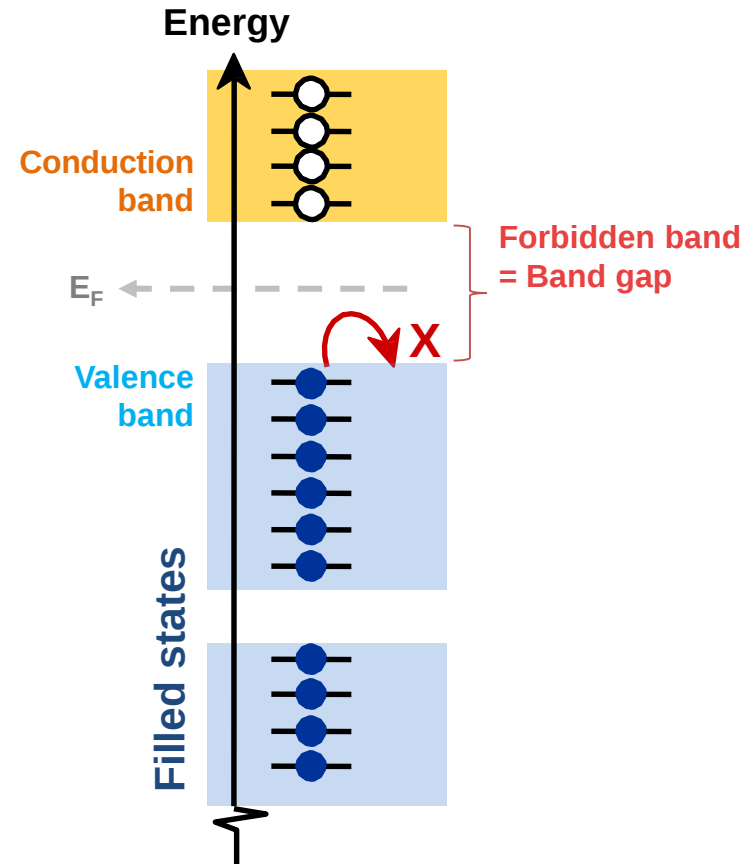
고온 또는 광자 흡수 시 전도 가능



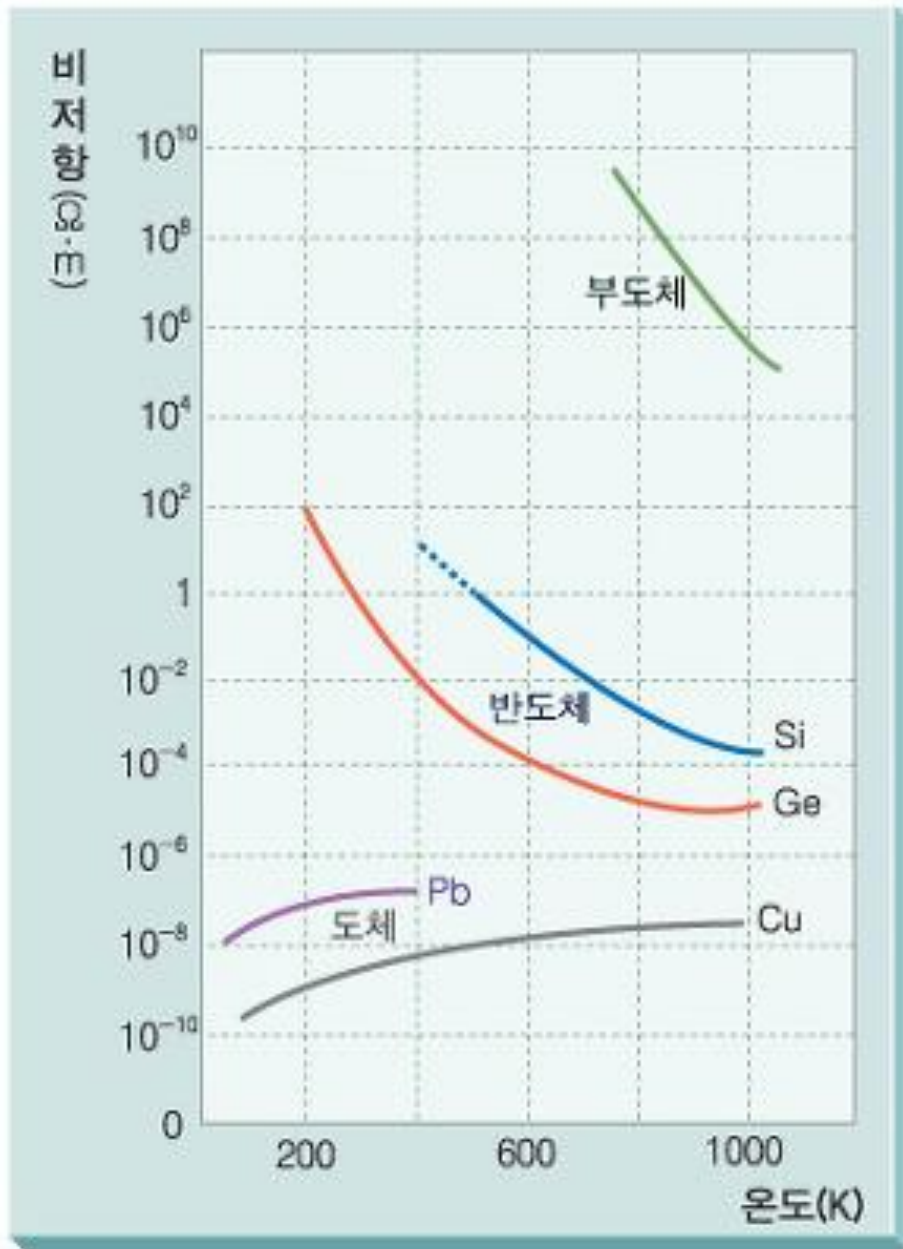
- **Insulators**

Large band gap (> 2 eV)

전도 불가능, Very high resistivity



Resistance-Temperature Relation



• Resistance-Temperature Relation

① $R_{\text{insulator}} \text{ \& } R_{\text{semiconductor}} \propto T^{-1}$

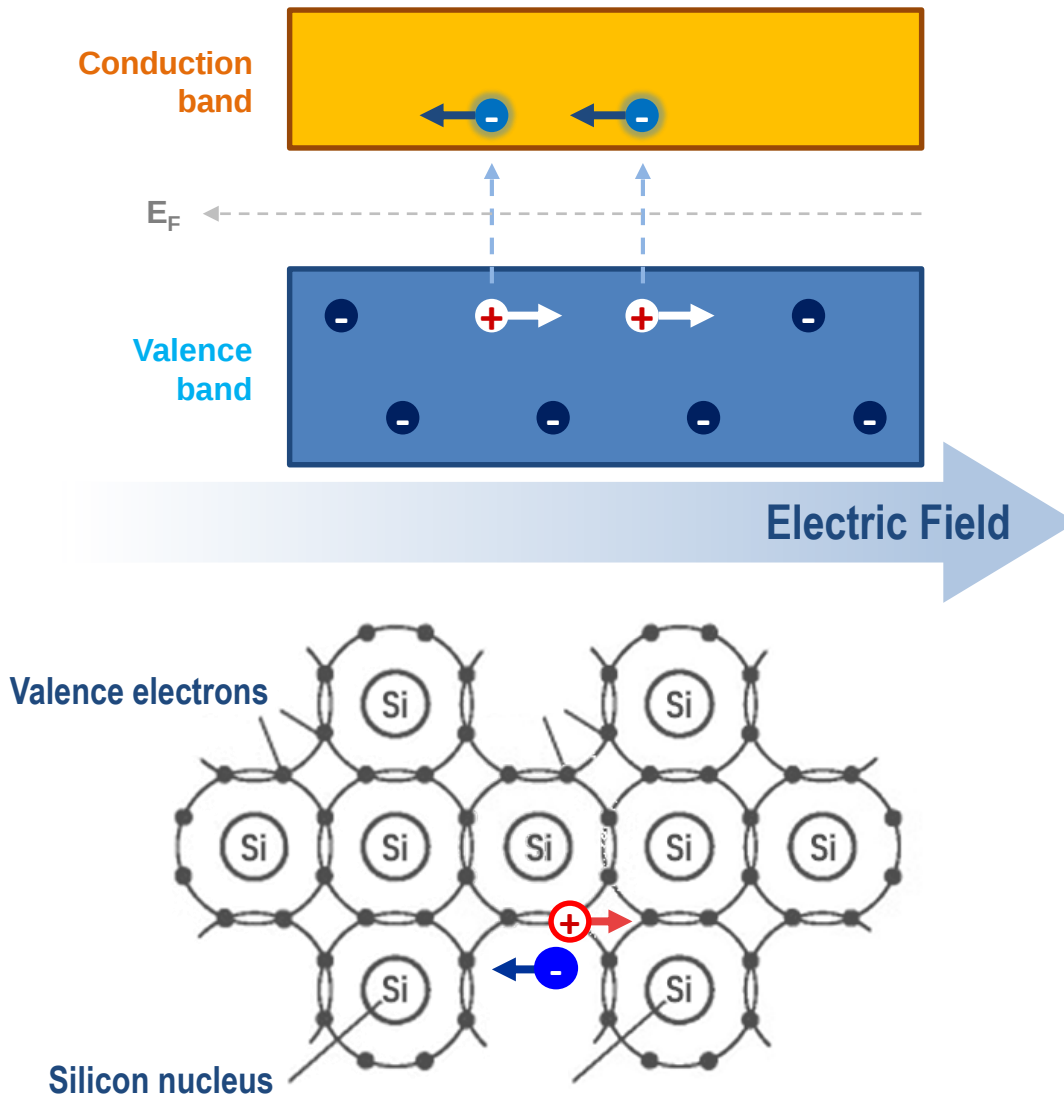
∴ carrier concentration ↑

② $R_{\text{conductor}} \propto T$

∴ thermally vibrating lattice atoms

Charge Carriers

Conductivity of Semiconductors



- **Electron**
(-) Charge Carrier

- **Hole**
(+) Charge Carrier

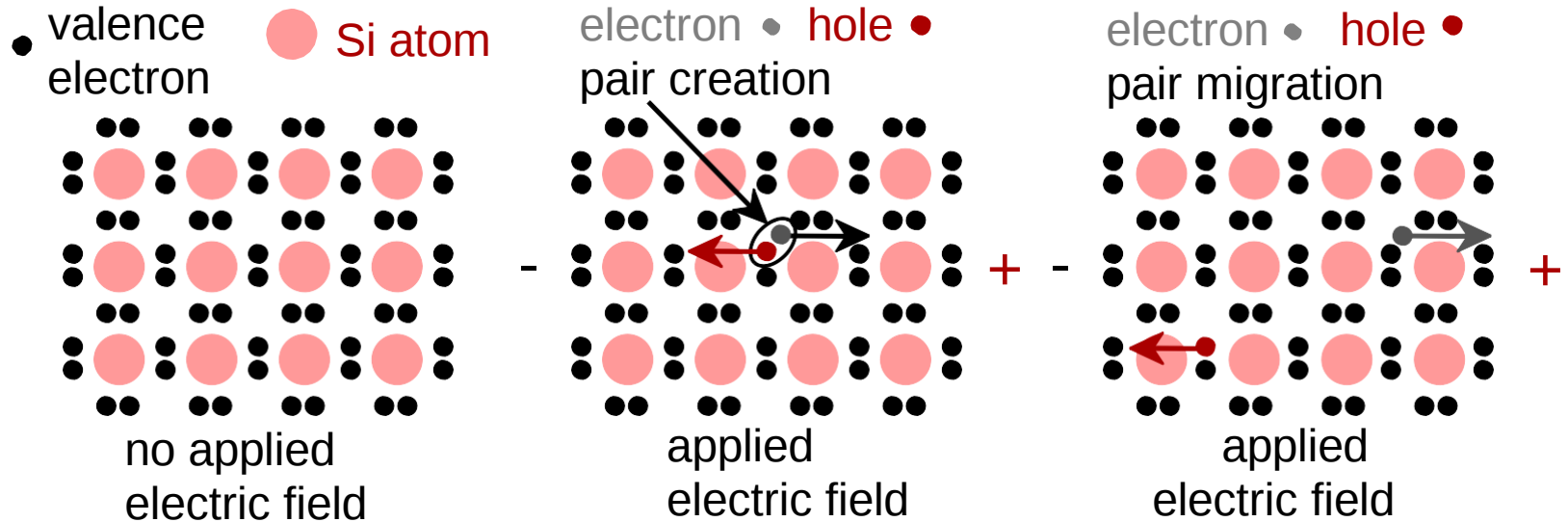
- **Conductivity**

$$\sigma = ne\mu_e$$

- **Mobility**

$$v_d = \mu_e E$$

Charge Carriers



Adapted from Fig. 18.11, Callister 7e.

• Conductivity of semiconductor

$$\sigma = ne\mu_e + pe\mu_h$$

electron mobility

hole mobility

Intrinsic & Extrinsic semiconductor

- **Intrinsic Semiconductor:**

순수한 재료의 전자 구조에 의해 반도체 특성을 가지는 경우

전자의 수 = 정공의 수 ($n=p$)

예) Si, Ge, GaAs 등

- **Extrinsic Semiconductor:**

도핑하여 extra 캐리어 (전자 또는 정공)를 부여

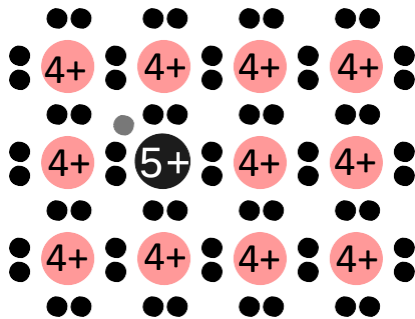
N-type: $n \gg p$

P-type: $p \gg n$

Intrinsic & Extrinsic semiconductor

- *n*-type ($n \gg p$)

● Phosphorus atom



no applied
electric field

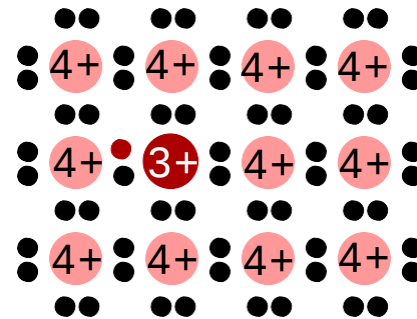
$$\sigma \approx ne\mu_e$$

- Hole
- Conduction electron
- Valence electron

● Si atom

- *p*-type ($p \gg n$)

● Boron atom



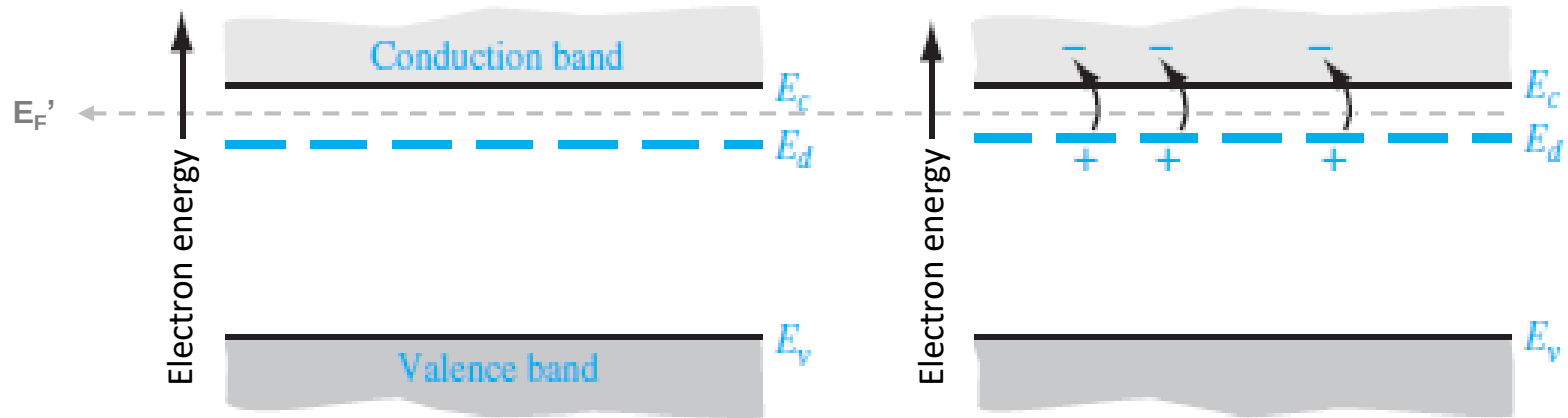
no applied
electric field

$$\sigma \approx pe\mu_h$$

Intrinsic & Extrinsic semiconductor

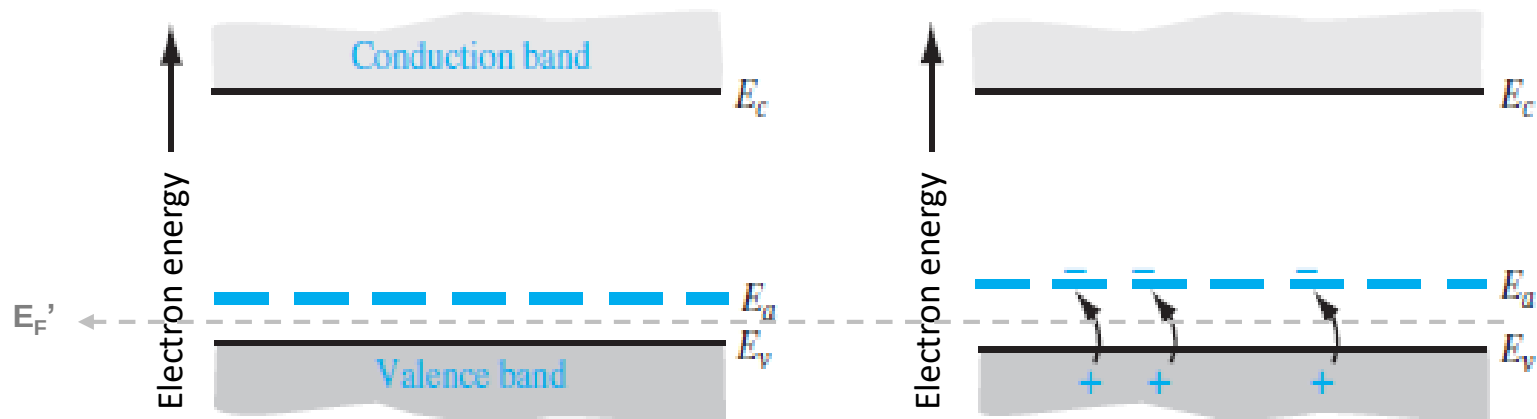
- ***n*-type**

Donor State $\rightarrow$ Conduction Band



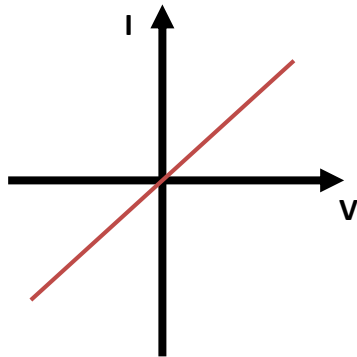
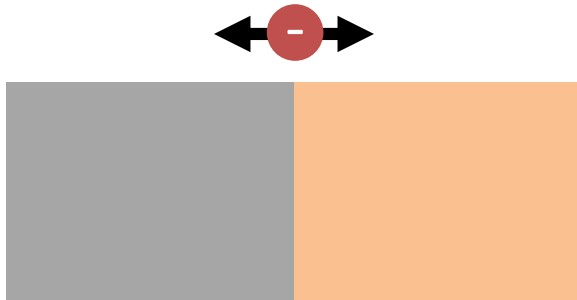
- ***p*-type**

Valence Band $\rightarrow$ Acceptor State

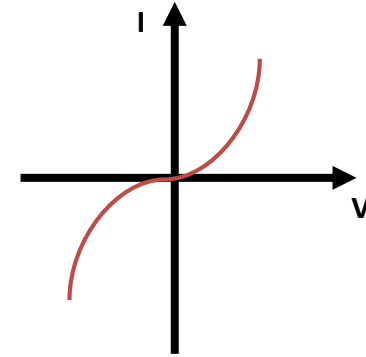
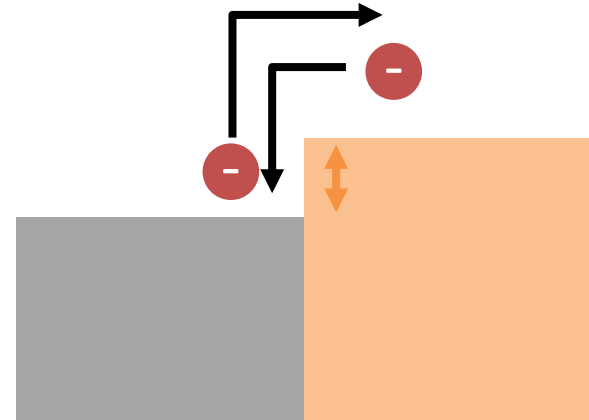


Ohmic Contact

- Ohmic Contact



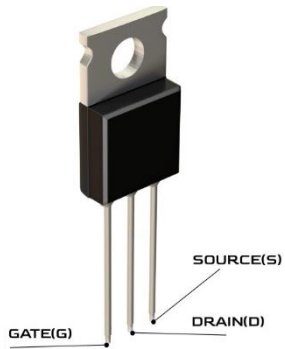
Ohmic Contact



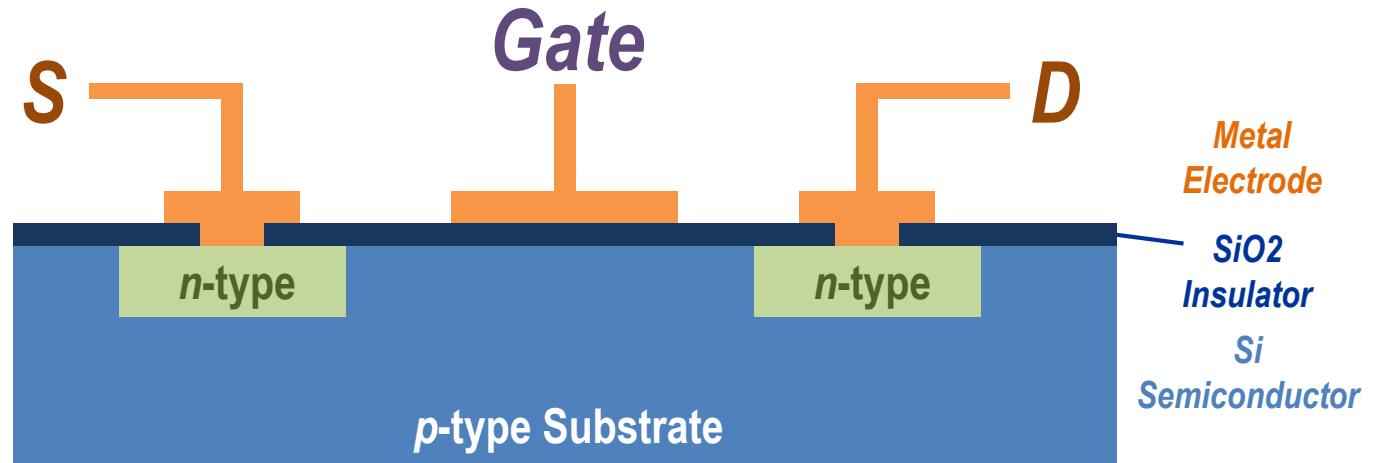
Non-Ohmic contact

MOSFET

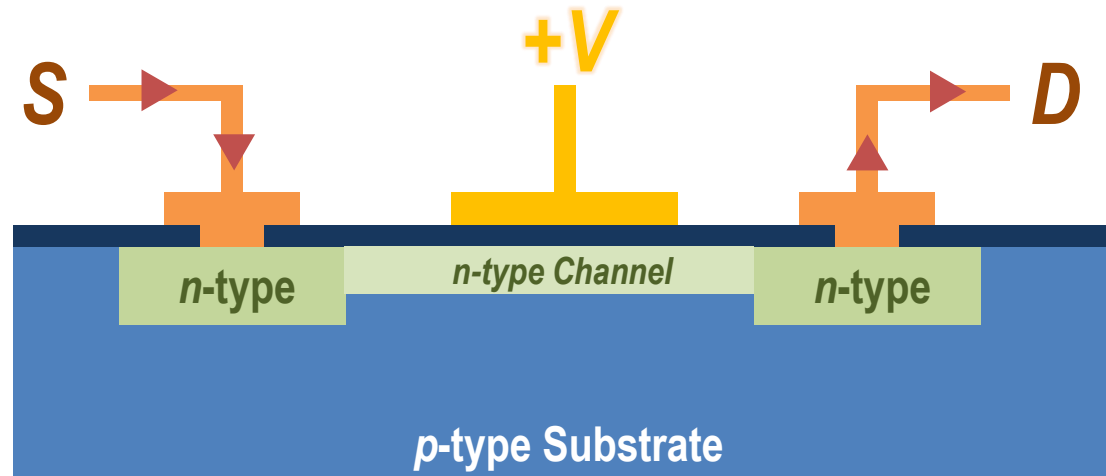
Metal Oxide Semiconductor Field Effect Transistor



$V_{\text{Gate}} = 0$
OFF state



$V_{\text{gate}} > 0$
ON state



어떻게 저런 구조로 만들 수 있었을까?

<https://www.youtube.com/watch?v=AcDn4bvW5IU>

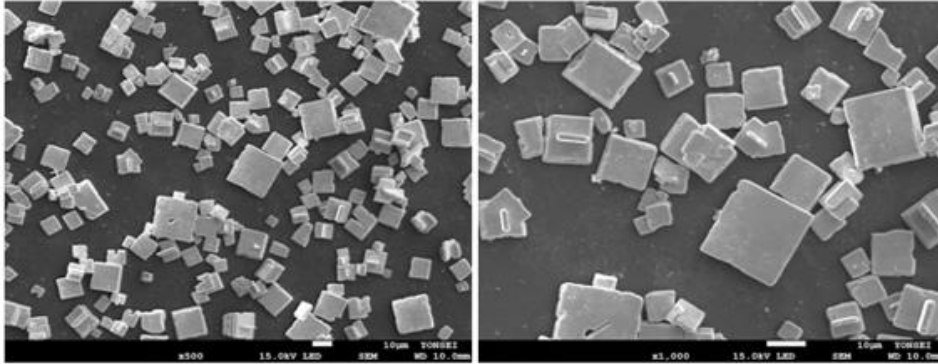
출처 : SK하이닉스 SK hynix

Experiment

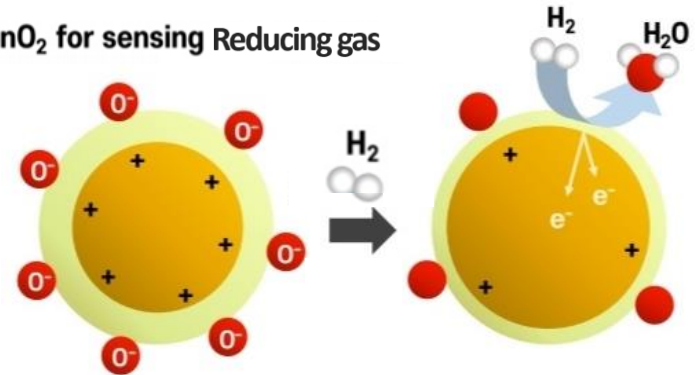


Oxide Semiconductor Gas Sensor

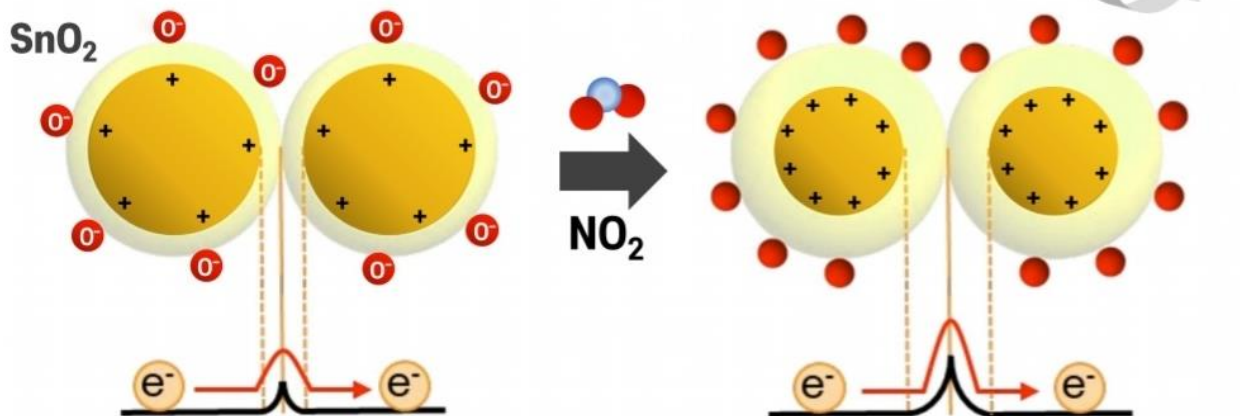
Mechanism



- SnO_2 for sensing Reducing gas



- SnO_2 for sensing oxidizing gas



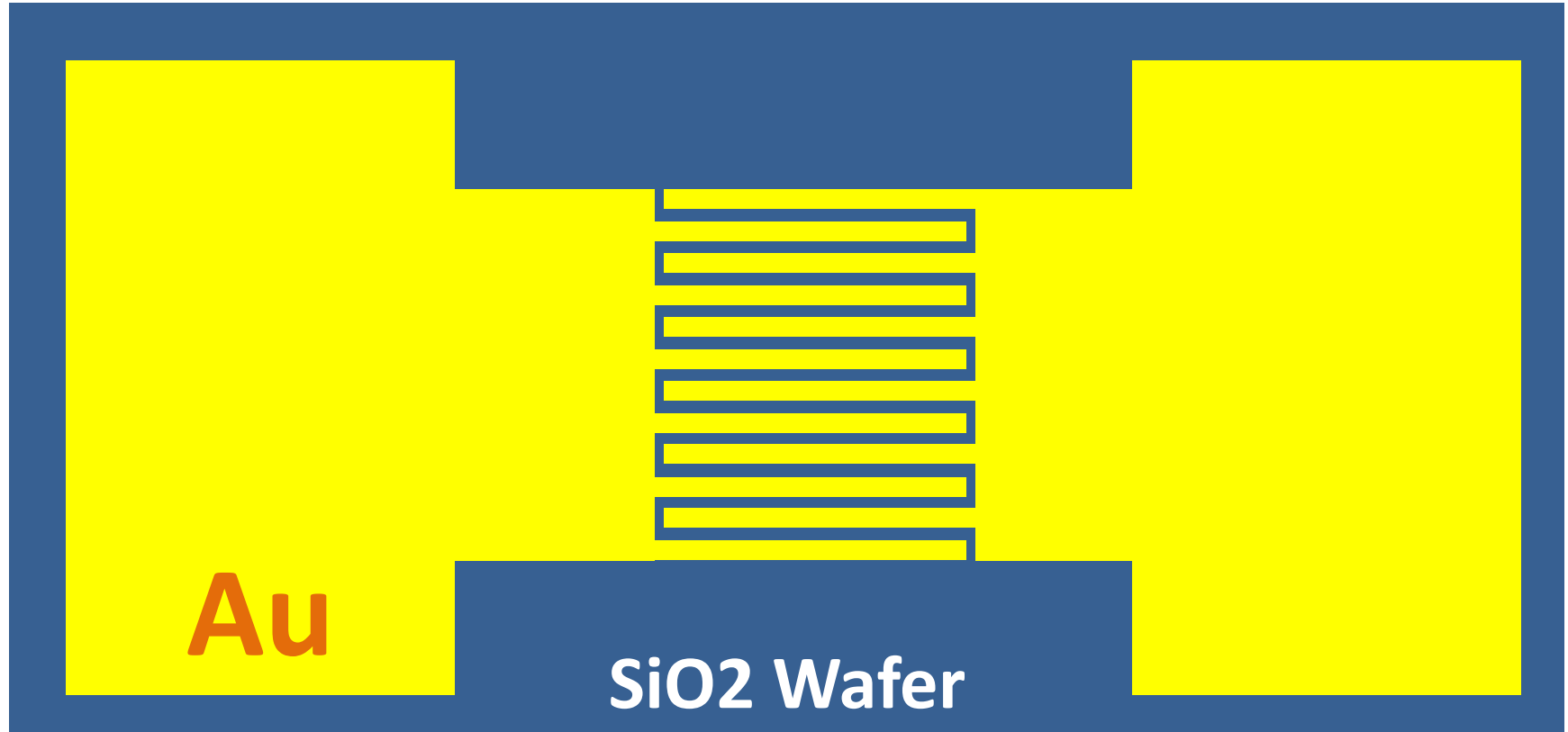
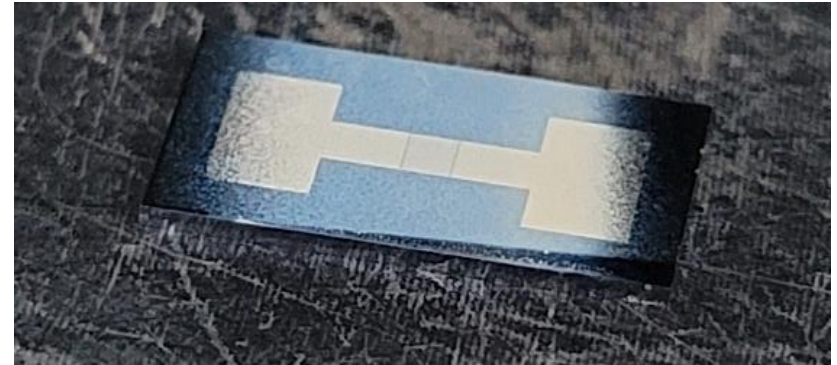
NO_2 exposure $\rightarrow$ Space charge layer expands $\rightarrow$ Resistance increases

Experiment



IDE (Interdigitated electrode)

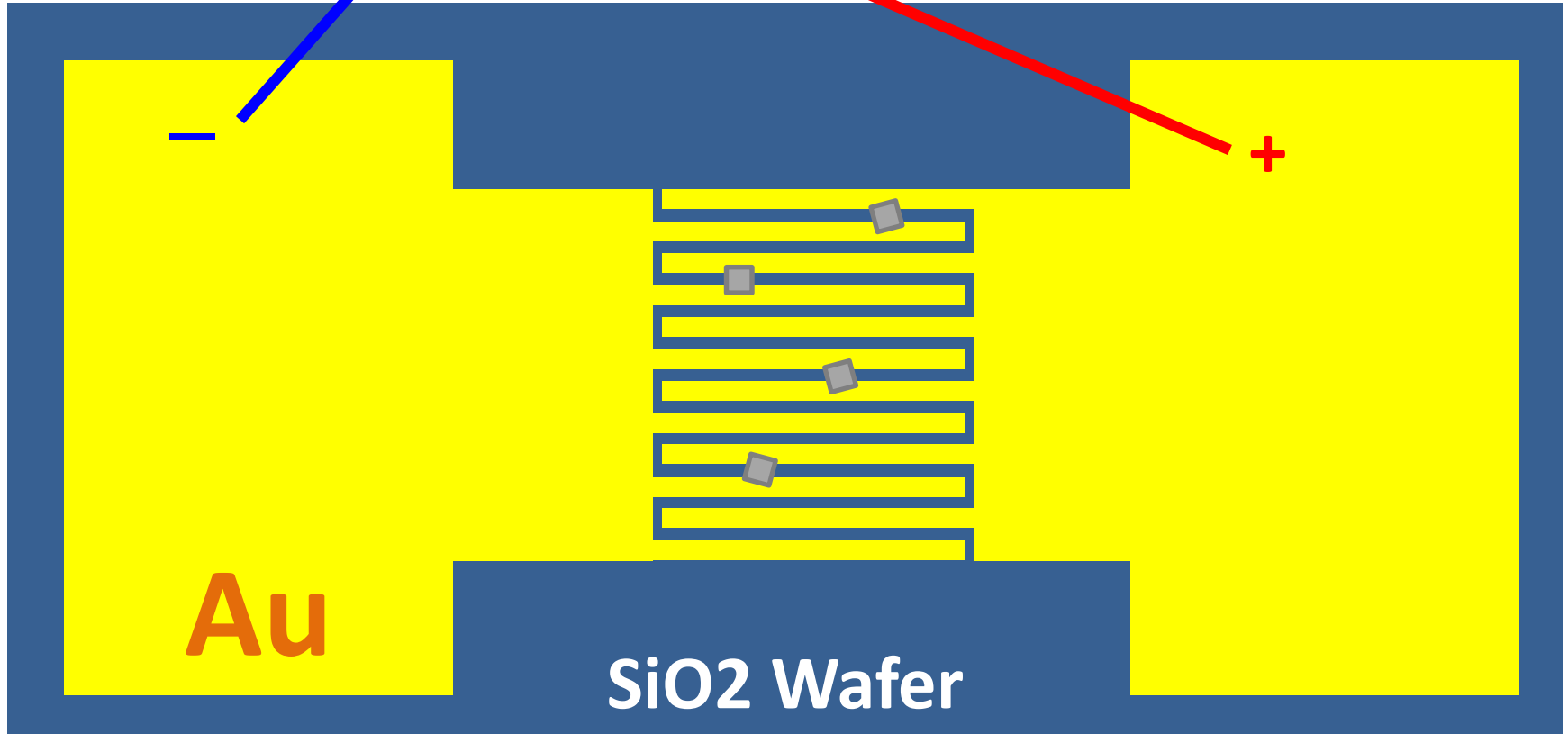
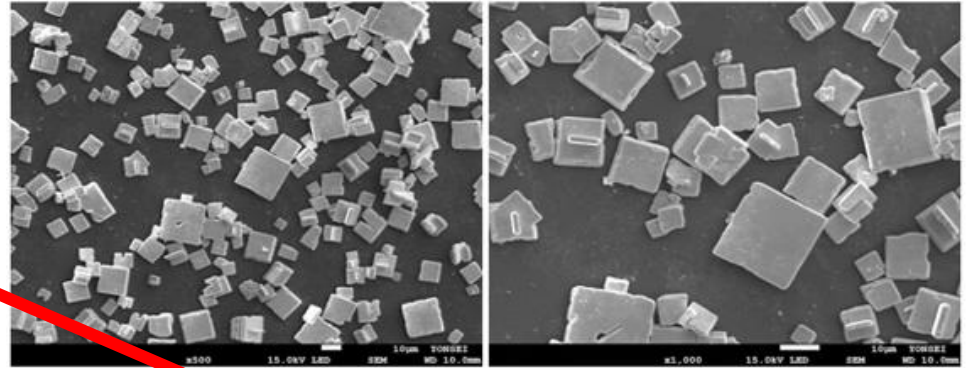
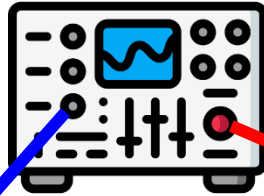
Fabricated by Sputter & Photolithography



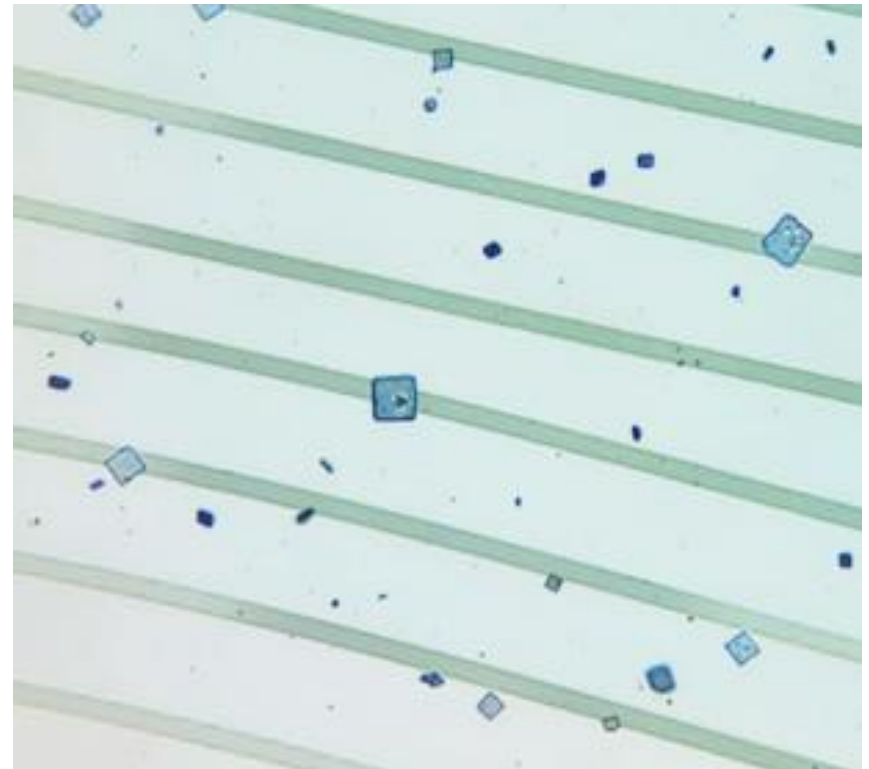
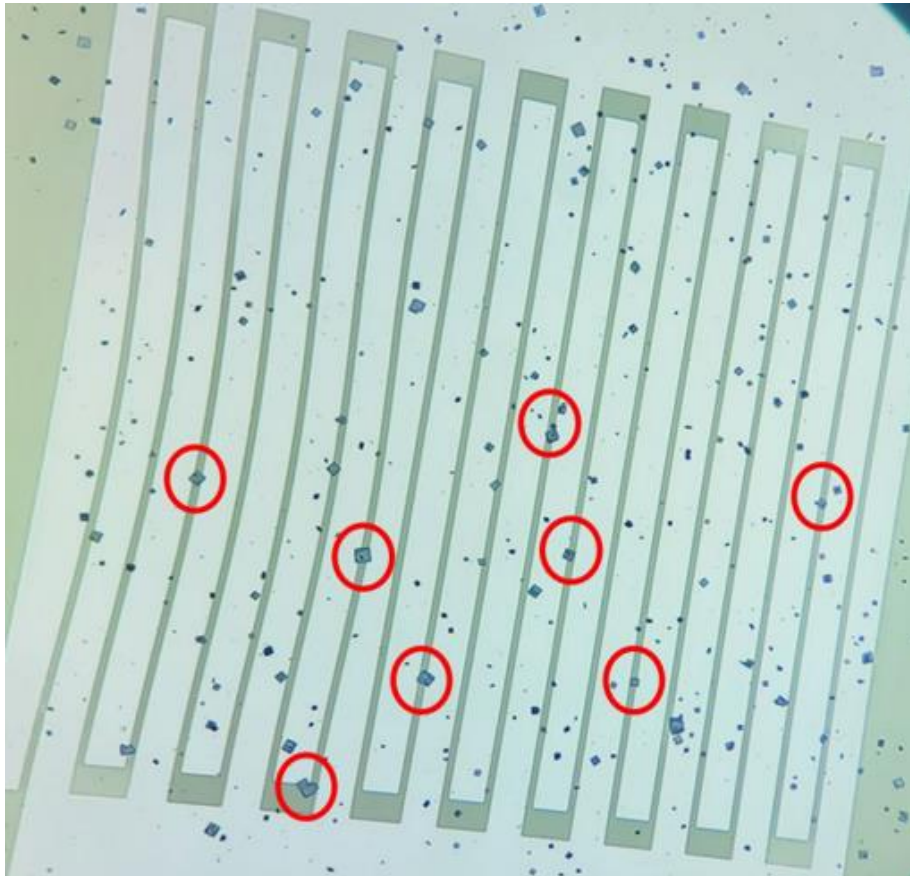
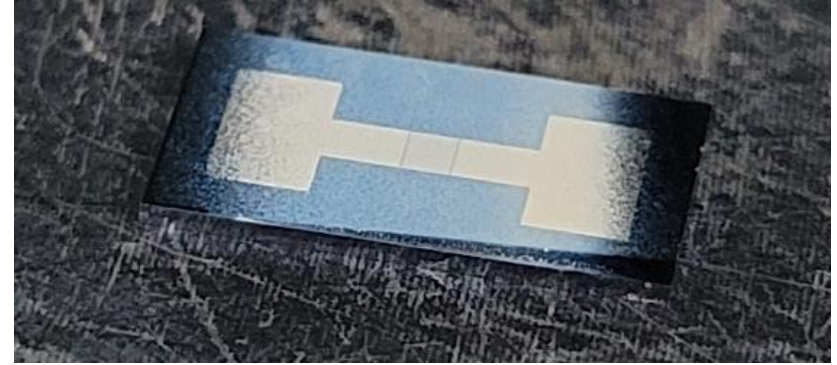
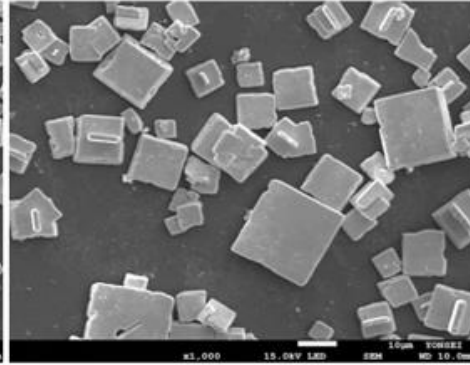
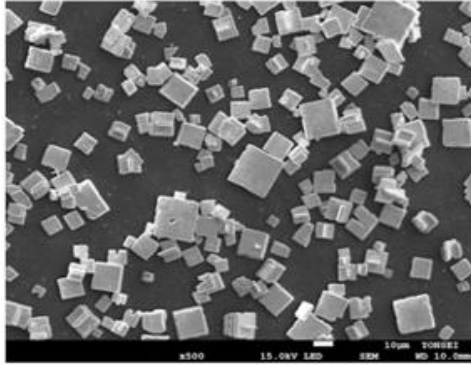
Experiment

ⓘ IDE (Interdigitated electrode)

$$V = I R$$

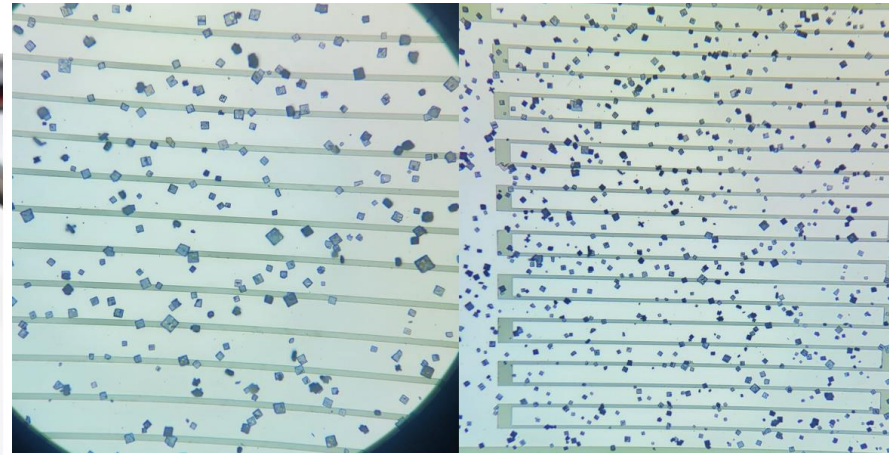
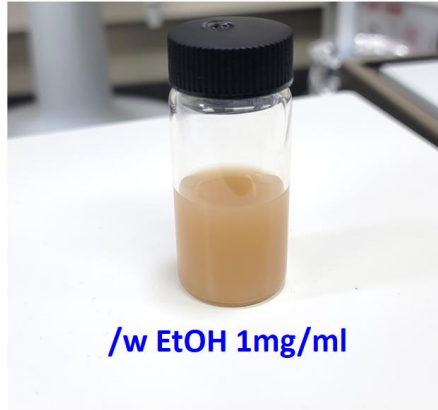


Experiment

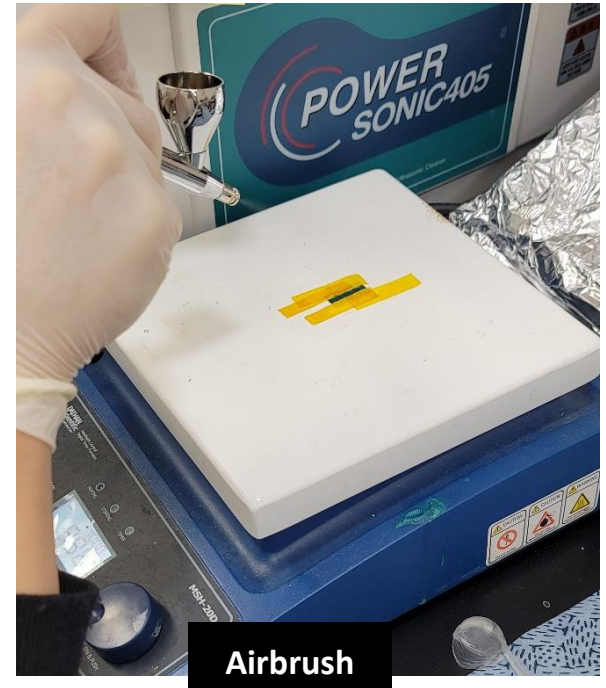
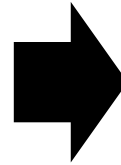
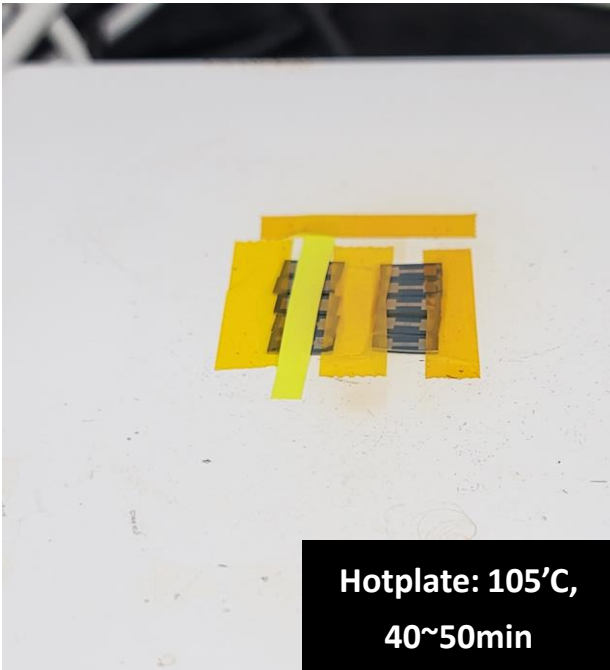


Experiment

Dispersion 용액 제작

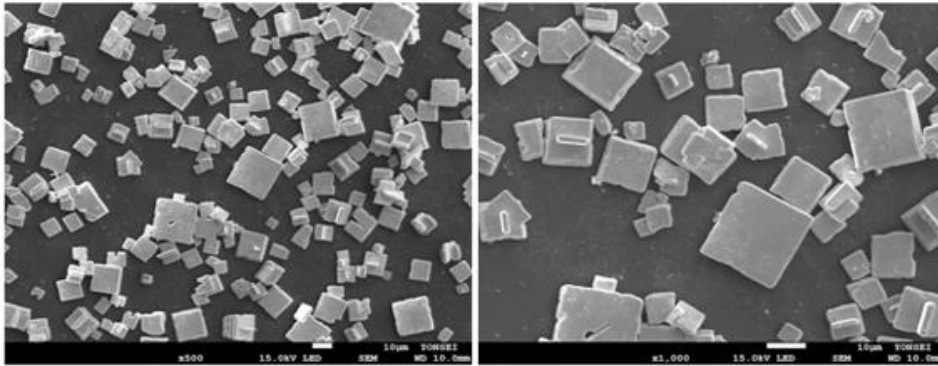


Airbrush 진행

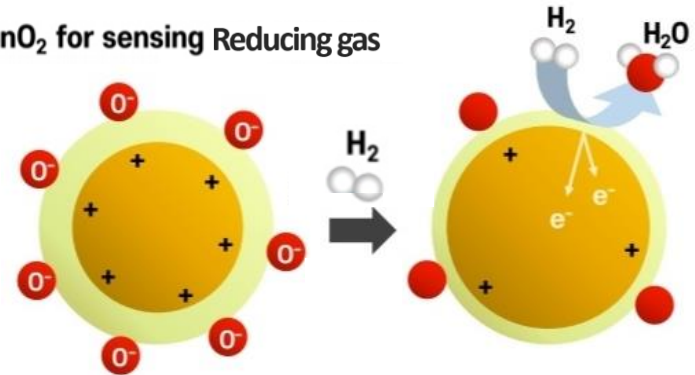


Experiment

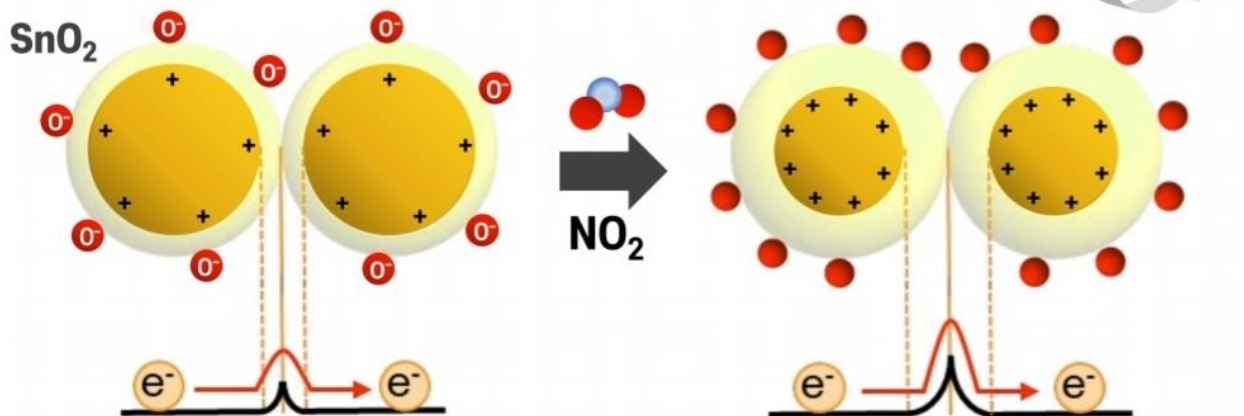
Metal Oxide Semiconductor Gas Sensor Mechanism



- SnO_2 for sensing Reducing gas



- SnO_2 for sensing oxidizing gas



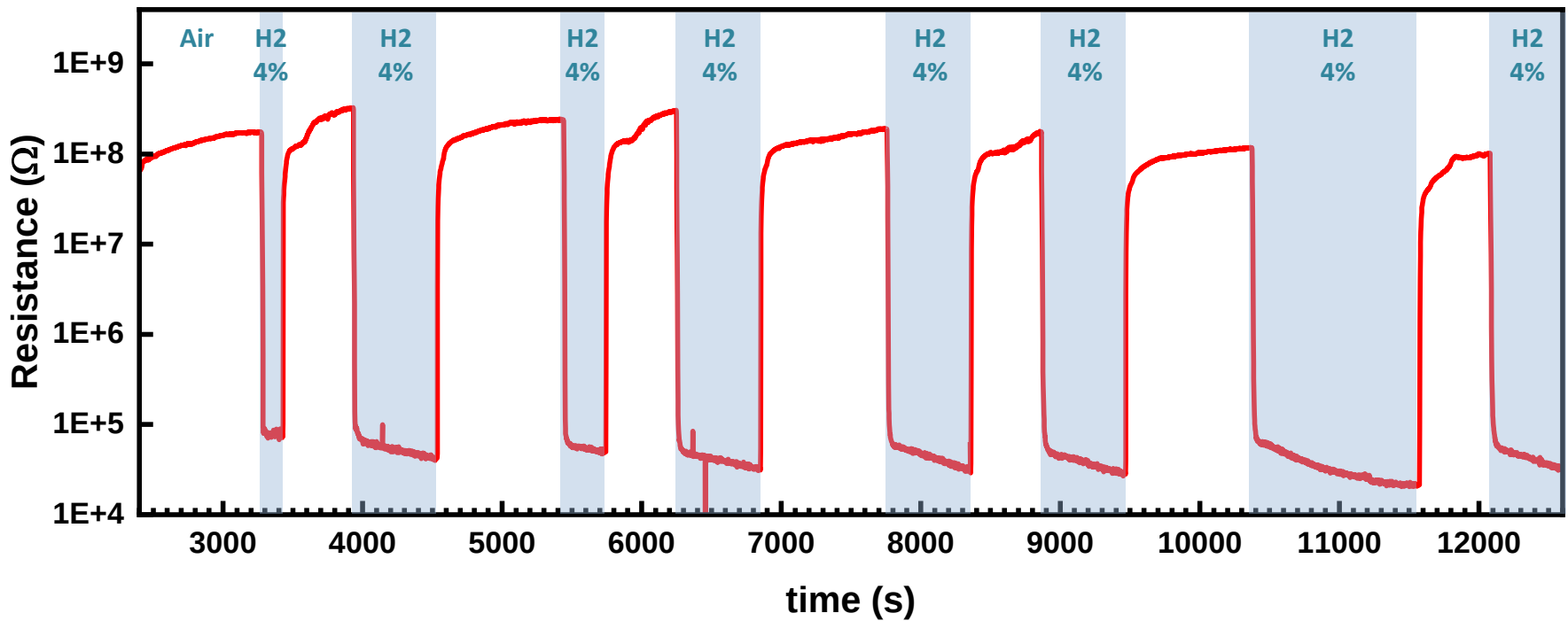
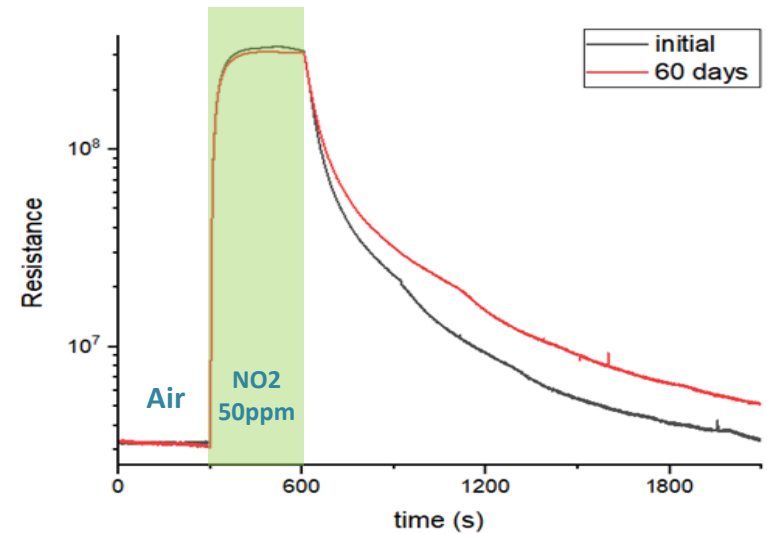
NO_2 exposure $\rightarrow$ Space charge layer expands $\rightarrow$ Resistance increases

Experiment



SnO-based gas sensor

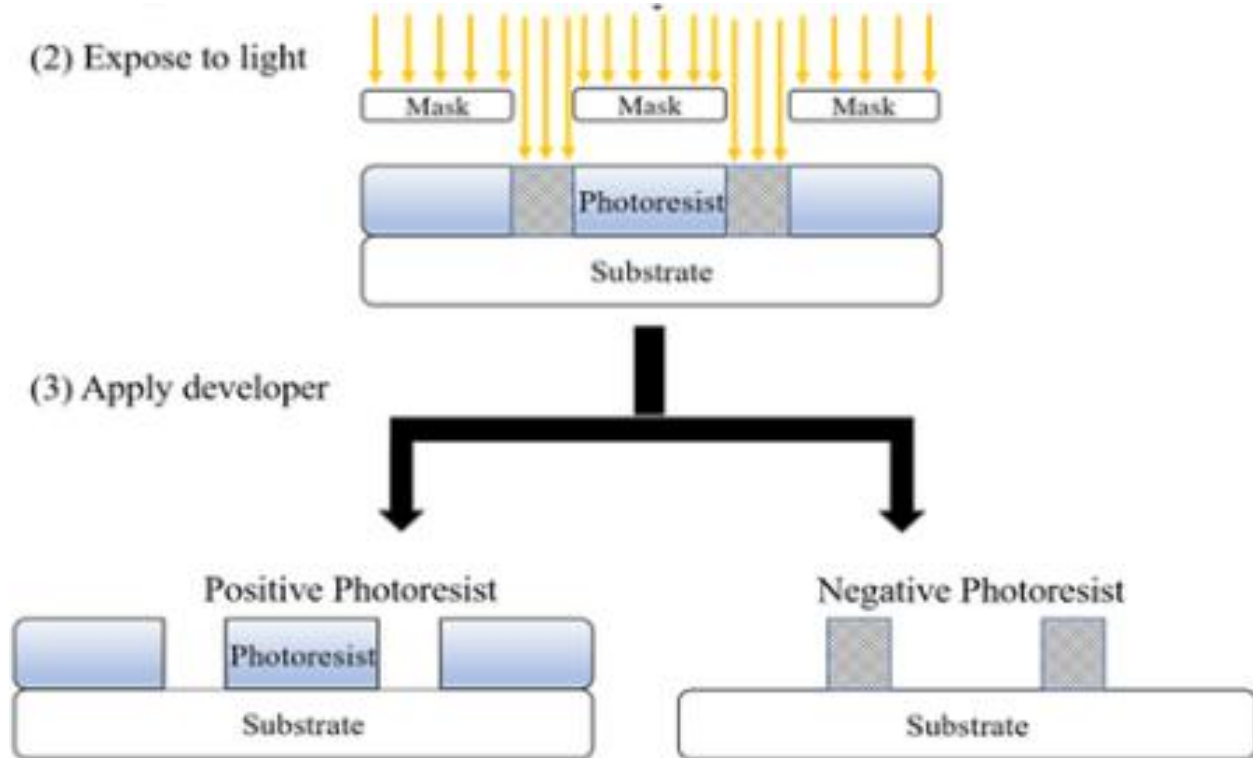
Results (4% H₂, 50ppm NO₂)



Experiment

- **Photoresist (PR)**

특정 파장의 빛에 의해
성질이 변하는 물질



- **Positive PR**

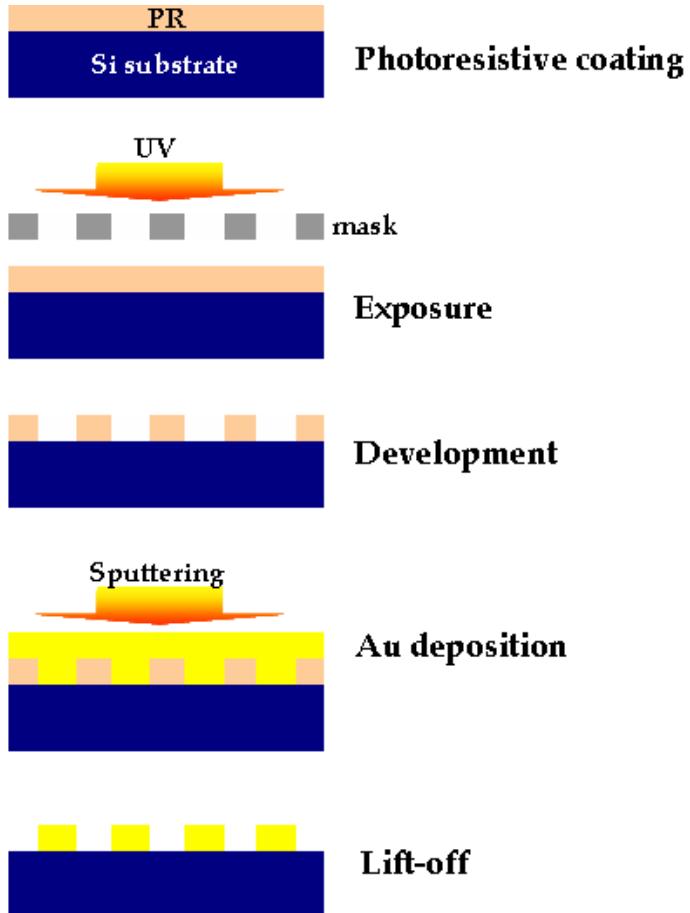
빛에 노출된 부분이 화학적인 분해로 인해 **Developer**에 씻겨 나감.
즉, Mask로 덮여 빛이 닿지 않은 부분이 남는다.

- **Negative PR**

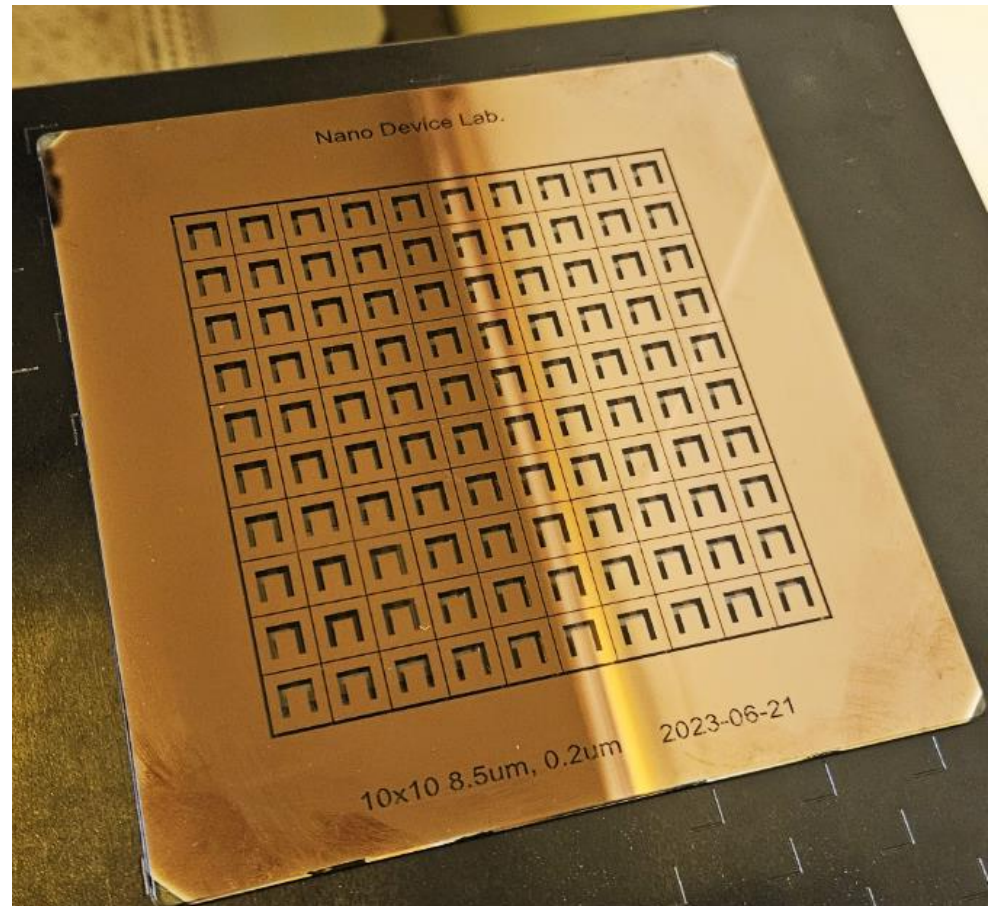
빛에 노출된 부분이 화학적인 결합으로 인해 **Developer**에 씻겨 나가지 않음.
즉, Mask로 덮여 빛이 닿지 않은 부분이 용해된다.

Experiment

- **Photolithography**
(Lift-off Process)

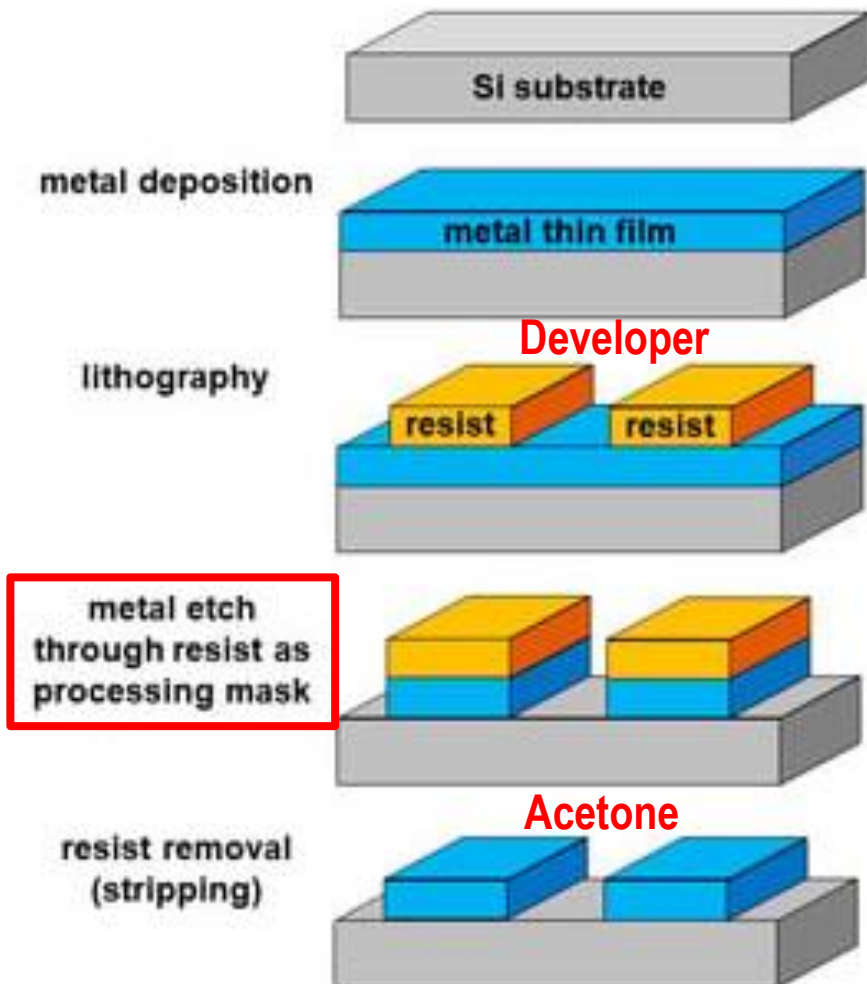


- **Photomask**

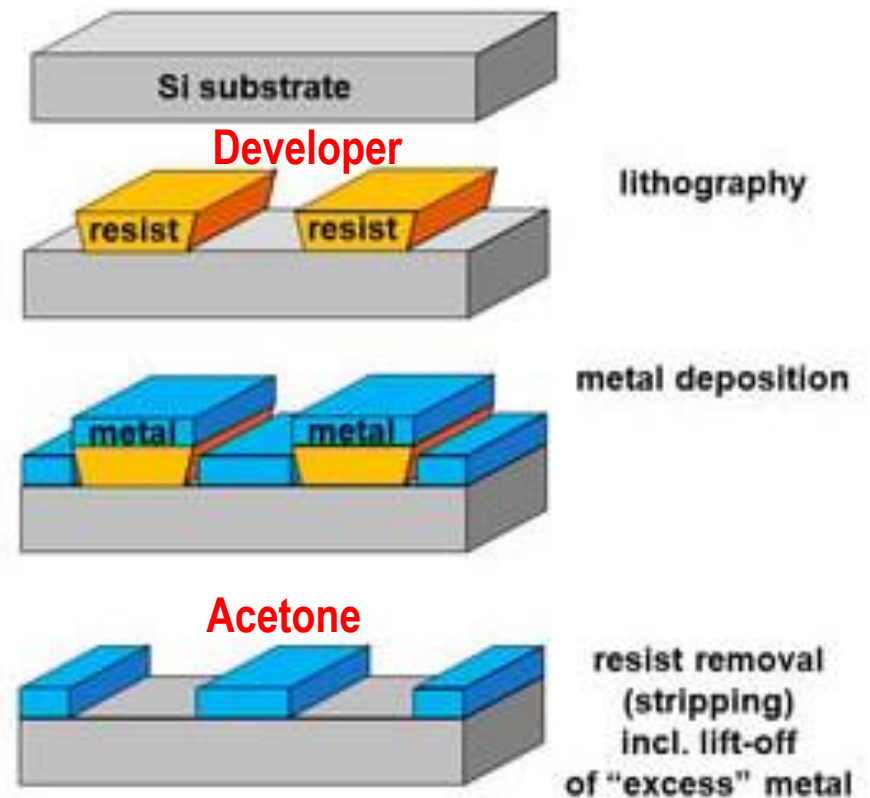


Experiment

Etch-back Process



Lift-off Process

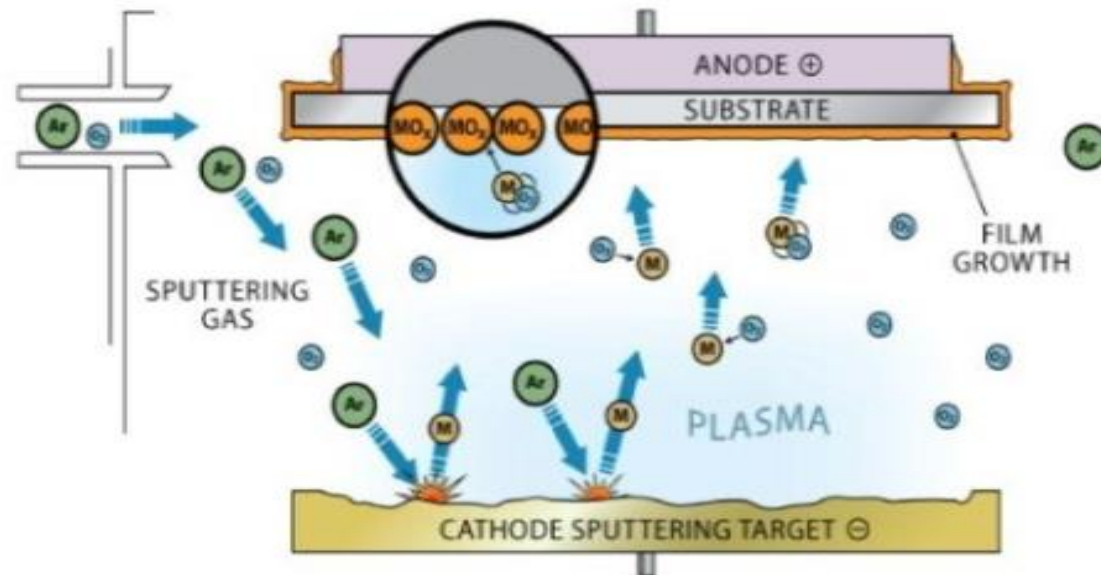
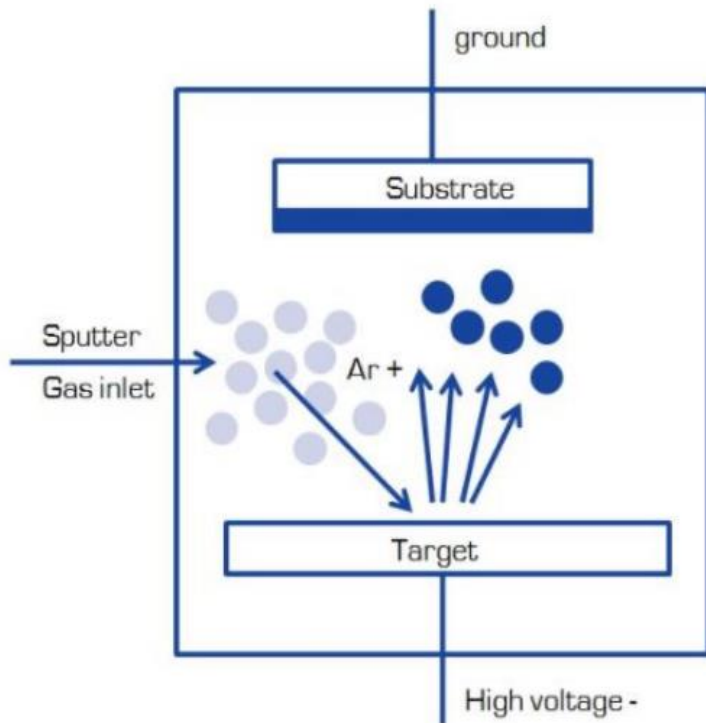


더 간단하지만
PR 두께가 두꺼워야 함
→ 미세패턴 형성 어려움

Experiment

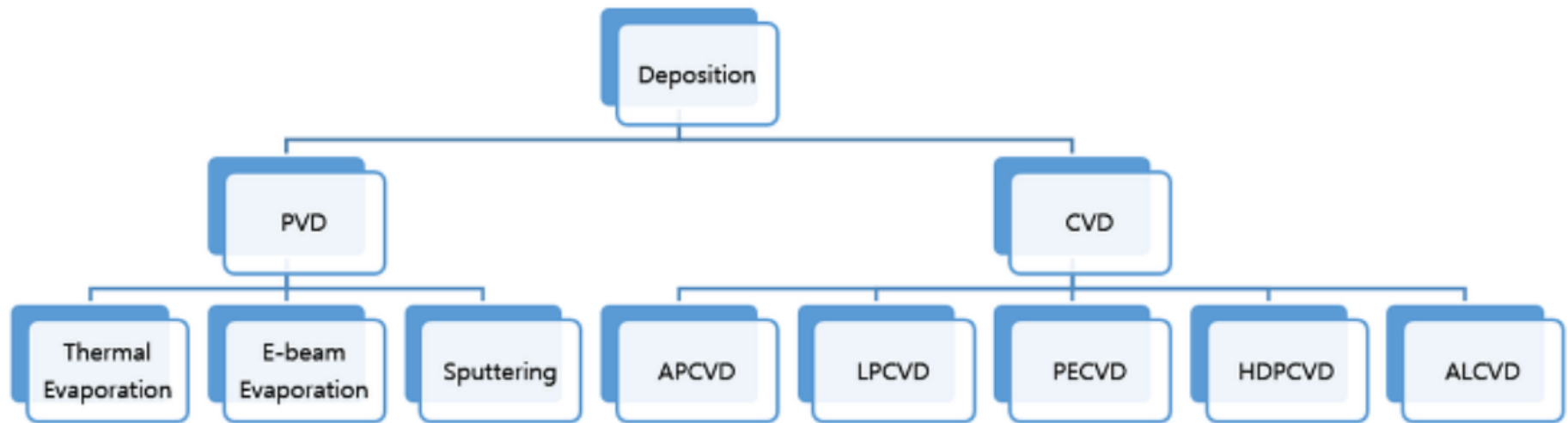
- **Sputtering**

이온화 된 가스 원자(Plasma)를 강한 전기장을 통해 타겟(Metal)에 충돌시켜
기판에 **금속 박막**을 형성하는 기술.



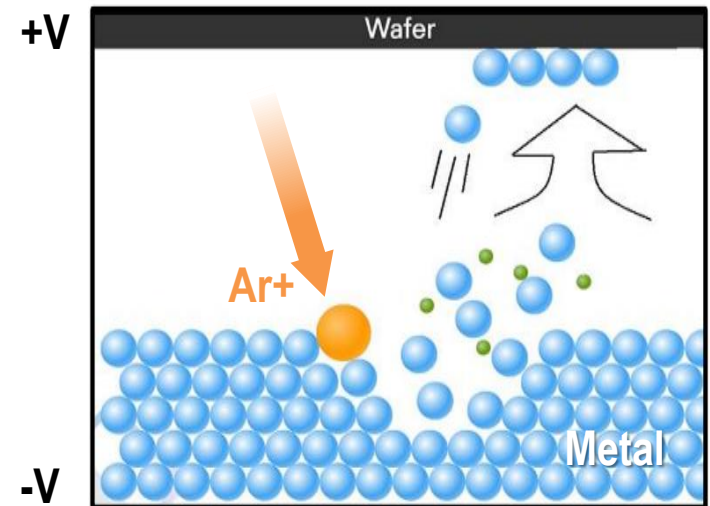
Target: Au, Ag, Pd, Pt, Cr...

Experiment



- Sputter는 PVD (Physical Vapor Deposition)의 일종이다.

- ① 챔버 내 Vacuum 조성
- ② 전자빔으로 Plasma 생성 (Ar^+)
- ③ 고전압으로 Ar^+ 가속 $\rightarrow$ 타겟(음극) 충돌
- ④ 튀어나온 타겟 Fragment가 기판에 증착



Experiment

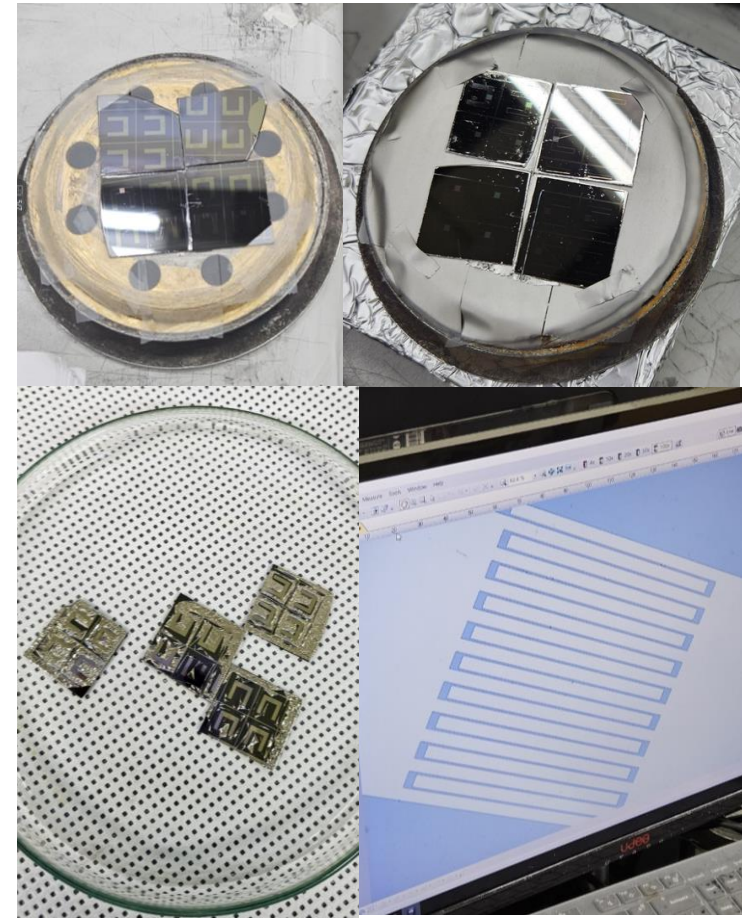
실험 (이번주 목) - 센서 소자 구현을 위한 IDE 제작

1. Photolithography (공B331)

- ① Si 기판 위에 Photo Resist 물질을 도포한다
- ② IDE 포토마스크를 이용하여 UV exposure 진행
- ③ Developer를 통해 UV 노출된 PR 제거
- ④ OM으로 관찰

2. Sputter & PR Removal (첨단관 지하 2층 214)

- ① PR 패터닝된 샘플을 스퍼터에 로딩
- ② 고진공을 잡는다
- ③ Ar 흘려주어 플라즈마 환경 조성 후 Au 박막 증착
- ④ 샘플 언로딩 후 Acetone에 담가 남은 PR을 제거한다.
- ④ OM으로 관찰



이론 및 실험 관련 퀴즈 (다음주 화)



재료의 전기적 성질

emph4sis

이 우 영
나노 소자 연구실
신소재공학과



YONSEI
UNIVERSITY